### **ABSOLUTE MAXIMUM RATINGS**

IN to GND0.3V to +6V	Continuous Power Dissipation ( $T_A = +70^{\circ}$ C)
C1+, SHDN to GND0.3V to (V <sub>IN</sub> + 0.3V)	6-Pin SOT23 (derate 14mW/°C above +70°C) (Note 5)1.1W
C1- to GND(V <sub>OUT</sub> - 0.3V) to + 0.3V	Operating Temperature Range40°C to +85°C
OUT to GND+0.3V to -6V	Junction Temperature Range40°C to +85°C
OUT Output Current	Storage Temperature Range65°C to +150°C
OUT Short-Circuit to GNDIndefinite	Lead Temperature(Note 6)

Note 5: Thermal properties are specified with product mounted on the PC board with one square-inch of copper area and still air.
Note 6: This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. Maxim recommends the use of the solder profiles recommended in the industry standard specification, JEDEC 020A, paragraph 7.6, Table 3 for IR/VPR and Convection reflow processes. Preheating, per this standard, is required. Hand or wave soldering is not recommended.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **ELECTRICAL CHARACTERISTICS**

(Circuit of Figure 1, capacitors from Table 2,  $V_{IN} = +5V$ ,  $\overline{SHDN} = IN$ ,  $T_A = 0^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	COND	ITIONS	MIN	TYP	MAX	UNITS	
	MAX1607P/S PL - 5KO	$T_A = +25^{\circ}C$	1.25		5.5		
Supply Voltage Papag	MAX 109/11/0, 11 - 0K22	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	1.5		5.5		
Supply Voltage halige		$T_A = +25^{\circ}C$	1.4		5.5	V	
	WAX 1097 1/0, nL = 3K22	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	1.5		5.5		
		MAX1697R		150	300		
Quiescent Supply Current		MAX1697S		350	650		
(Note 9)	IA = +25 C	MAX1697T		950	1700	μΑ	
		MAX1697U		1800	3400		
Chutdouro Cupolu Current		$T_A = +25^{\circ}C$		0.002	1	μΑ	
Shuldown Supply Current	SHDN = GND	$T_A = +85^{\circ}C$		0.03			
Short-Circuit Current	Output shorted to ground, $T_A = +25^{\circ}C$			170		mA	
Oscillator Frequency	T <sub>A</sub> = +25°C	MAX1697R	7	12	17		
		MAX1697S	20	35	50	kHz	
		MAX1697T	70	125	180		
		MAX1697U	140	250	360		
Voltage Conversion Efficiency	I <sub>OUT</sub> = 0, T <sub>A</sub> = +25°C		99	99.9		%	
Output Desistence (Nate 7)		$T_A = +25^{\circ}C$		12	25	Ω	
Oulput Resistance (Note 7)	IOUT = 0011A	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$			33		
OUT to GND Shutdown Resistance	SHDN = GND, OUT is internally pulled to GND in shutdown			3	8	Ω	
	$2.5V \le V_{IN} \le 5.5V$		2.0				
SHDN Input Logic High	$V_{\rm IN(MIN)} \le V_{\rm IN} \le 2.5 V$		V <sub>IN</sub> - 0.2			V	
	$2.5V \le V_{\text{IN}} \le 5.5V$				0.6		
SHDN Input Logic Low	$V_{IN(MIN)} \le V_{IN} \le 2.5V$				0.2	V	
		$T_A = +25^{\circ}C$	-100	0.05	+100	20	
SHDIN Blas Current		$T_A = +85^{\circ}C$		10		nA	



## **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1, capacitors from Table 2,  $V_{IN} = +5V$ ,  $\overline{SHDN} = IN$ ,  $T_A = 0^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	COND	ITIONS	MIN	ТҮР	MAX	UNITS	
Wake-Up Time from Shutdown		MAX1697R		1200			
	Iout = 15mA	MAX1697S		600			
		MAX1697T		100		μs	
		MAX1697U		70			
THERMAL SHUTDOWN							
Trip Temperature	Temperature increasing			150		°C	
Hysteresis				15		°C	

## **ELECTRICAL CHARACTERISTICS**

(Circuit of Figure 1, capacitors from Table 2,  $V_{IN} = +5V$ ,  $\overline{SHDN} = IN$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted.) (Note 8)

PARAMETER	CONDITIONS		MIN	MAX	UNITS
Supply Voltage Bange		MAX1697R/S	1.5	5.5	V
	MAX169	MAX1697T/U	1.6	5.5	
Output Current	Continuous, long-term			60	mA <sub>RMS</sub>
	MAX1697R			350	
Quiescent Current (Note 9)	MAX1697S			750	
	MAX1697T			1800	μΑ
	MAX1697U			3600	1
Oscillator Frequency	MAX1697R		6	21	kHz
	MAX1697S		16	60	
	MAX1697T		60	200	
	MAX1697U		120	400	
Output Resistance (Note 7)	I <sub>OUT</sub> = 60mA			33	Ω
OUT to GND Shutdown Resistance	$\overline{\text{SHDN}}$ = GND, OUT is internally pulled to GND in shutdown			8	Ω
	$2.5V \le V_{IN} \le 5.5V$		2.1		V
	$V_{IN(MIN)} \le V_{IN} \le 2.5V$		VIN - 0.2		
	$2.5V \le V_{IN} \le 5.5V$			0.6	V
	$V_{IN(MIN)} \le V_{IN} \le 2.5V$			0.2	

Note 7: Output resistance is guaranteed with capacitor ESR of  $0.3\Omega$  or less.

Note 8: All specifications from -40°C to +85°C are guaranteed by design, not production tested.

**Note 9:** The MAX1697 may draw high supply current during startup, up to the minimum operating supply voltage. To guarantee proper startup, the input supply must be capable of delivering 90mA more than the maximum load current.



**MAX1697** 

**Typical Operating Characteristics (continued)** 



## **Typical Operating Characteristics (continued)**

MAX1697R OUTPUT CURRENT

M XX M

(Circuit of Figure 1, capacitors from Table 2, VIN = +5V, SHDN = IN, TA = +25°C, unless otherwise noted.)



### **Typical Operating Characteristics (continued)**

(Circuit of Figure 1, capacitors from Table 2,  $V_{IN} = +5V$ ,  $\overline{SHDN} = IN$ ,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



#### MAX1697U **OUTPUT RIPPLE vs. CAPACITANCE** 500 450 400 350 OUTPUT RIPPLE (mV) 300 250 200 +4.75V, 4.0V V<sub>OUT</sub> = 150 V<sub>IN</sub> = +3.15V, V<sub>OUT</sub> = -2.5V 100 $V_{IN} = +1.9V, V_{OUT} = -1.5V$ 50 0 0 1 2 3 4 5 6 7 8 9 10 CAPACITANCE (µF)



Figure 1. Typical Application Circuit

C2 is smaller than the voltage across C1, charge flows from C1 to C2 until the voltage across C2 reaches -V<sub>IN</sub>. The actual voltage at the output is more positive than -V<sub>IN</sub>, since switches S1–S4 have resistance and the load drains charge from C2.

#### **Efficiency Considerations**

The efficiency of the MAX1697 is dominated by its quiescent supply current (I<sub>Q</sub>) at low output current and by its output impedance ( $R_{OUT}$ ) at higher output current; it is given by:

$$\eta \cong \frac{I_{OUT}}{I_{OUT} + I_Q} \left( 1 - \frac{I_{OUT} \times R_{OUT}}{V_{IN}} \right)$$

## **Pin Description**

PIN	NAME	FUNCTION
1	OUT	Inverting Charge-Pump Output
2	IN	Power-Supply Voltage Input. Input range is 1.5V to 5.5V.
3	C1-	Negative Terminal of the Flying Capacitor
4	GND	Ground
5	SHDN	Shutdown Input. Drive this pin high for normal operation; drive it low for shutdown mode. OUT is actively pulled to ground during shutdown.
6	C1+	Positive Terminal of the Flying Capacitor

## **Detailed Description**

The MAX1697 capacitive charge pumps invert the voltage applied to their input. For highest performance, use low equivalent series resistance (ESR) capacitors (e.g., ceramic).

During the first half-cycle, switches S2 and S4 open, switches S1 and S3 close, and capacitor C1 charges to the voltage at IN (Figure 2). During the second half-cycle, S1 and S3 open, S2 and S4 close, and C1 is level shifted downward by  $V_{IN}$  volts. This connects C1 in parallel with the reservoir capacitor C2. If the voltage across





Figure 2. Ideal Voltage Inverter

MAX1697



Figure 3a. Switched-Capacitor Model

where the output impedance is roughly approximated by:

$$R_{OUT} \cong \frac{1}{\left(f_{OSC}\right) \times C1} + 2R_{SW} + 4ESR_{C1} + ESR_{C2}$$

The first term is the effective resistance of an ideal switched-capacitor circuit (Figures 3a and 3b), and R<sub>SW</sub> is the sum of the charge pump's internal switch resistances (typically  $4\Omega$  to  $5\Omega$  at V<sub>IN</sub> = +5V). The typical output impedance is more accurately determined from the *Typical Operating Characteristics*.

#### **Current Limit**

The MAX1697 limits its input current upon start-up to 170mA (typ). This prevents low-current or higher output impedance input supplies (such as alkaline cells) from being overloaded when power is applied or when the device awakes from shutdown.

#### Shutdown

The MAX1697 has a logic-controlled shutdown input. Driving SHDN low places the device in a low-power shutdown mode. The charge-pump switching halts, supply current is reduced to 2nA, and OUT is actively pulled to ground through a  $3\Omega$  resistance.

Driving SHDN high will restart the charge pump. The switching frequency and capacitor values determine how soon the device will reach 90% of the input voltage.



Figure 3b. Equivalent Circuit

#### **Thermal Shutdown**

The MAX1697 has a thermal shutdown mode for additional protection against fault conditions. When the temperature of the die exceeds +150°C, the internal clock stops, suspending the device's operation. The MAX1697 resumes operation when the die temperature falls 15°C. This prevents the device from rapidly oscillating around the temperature trip point.

### **Applications Information**

#### **Capacitor Selection**

The charge-pump output resistance is a function of the ESR of C1 and C2. To maintain the lowest output resistance, use capacitors with low ESR. (See Table 1 for a list of recommended manufacturers.) Tables 2 and 3 suggest capacitor values for minimizing output resistance or capacitor size.

#### Flying Capacitor (C1)

Increasing the flying capacitor's value reduces the output resistance. Above a certain point, increasing C1's capacitance has negligible effect because the output resistance is then dominated by internal switch resistance and capacitor ESR.

#### **Output Capacitor (C2)**

Increasing the output capacitor's value reduces the output ripple voltage. Decreasing its ESR reduces both output resistance and ripple. Lower capacitance values can be used with light loads if higher output ripple can be tolerated. Use the following equation to calculate the peak-to-peak ripple:

$$V_{\text{RIPPLE}} = \frac{I_{\text{OUT}}}{2(f_{\text{OSC}})C2} + 2 \times I_{\text{OUT}} \times \text{ESR}_{C2}$$

#### Input Bypass Capacitor (C3)

If necessary, bypass the incoming supply to reduce its AC impedance and the impact of the MAX1697's switching noise. A bypass capacitor with a value equal to that of C1 is recommended.



#### **Voltage Inverter**

The most common application for these devices is a charge-pump voltage inverter (Figure 1). This application requires only two external components—capacitors C1 and C2—plus a bypass capacitor, if necessary. Refer to the *Capacitor Selection* section for suggested capacitor types.

#### **Cascading Devices**

Two devices can be cascaded to produce an even larger negative voltage (Figure 4). The unloaded output voltage is normally -2 ×  $V_{IN}$ , but this is reduced slightly by the output resistance of the first device multiplied by the quiescent current of the second. When cascading more than two devices, the output resistance rises dramatically. For applications requiring larger negative voltages, see the MAX865 and MAX868 data sheets. The maximum load current and startup current of the nth cascaded circuit must not exceed the maximum output current capability of the (n-1)th circuit to ensure proper startup.

#### **Paralleling Devices**

Paralleling multiple MAX1697s reduces the output resistance. Each device requires its own pump capacitor (C1), but the reservoir capacitor (C2) serves all devices (Figure 5). Increase C2's value by a factor of n, where n is the number of parallel devices. Figure 5 shows the equation for calculating output resistance.

#### **Combined Doubler/Inverter**

In the circuit of Figure 6, capacitors C1 and C2 form the inverter, while C3 and C4 form the doubler. C1 and C3 are the pump capacitors; C2 and C4 are the reservoir capacitors. Because both the inverter and doubler use part of the charge-pump circuit, loading either output causes both outputs to decline toward GND. Make sure the sum of the currents drawn from the two outputs does not exceed 60mA.

#### Heavy Load Connected to a Positive Supply

Under heavy loads, where a higher supply is sourcing current into OUT, the OUT supply must not be pulled above ground. Applications that sink heavy current into OUT require a Schottky diode (1N5817) between GND and OUT, with the anode connected to OUT (Figure 7).

#### Layout and Grounding

Good layout is important, primarily for good noise performance. To ensure good layout, mount all components as close together as possible, keep traces short to minimize parasitic inductance and capacitance, and use a ground plane.

### Table 1. Low-ESR Capacitor Manufacturers

PRODUCTION METHOD	MANUFACTURER	SERIES	PHONE	FAX
	AVX	TPS series	803-946-0690	803-626-3123
Surface-Mount Tantalum	Matsuo	267 series	714-969-2491	714-960-6492
	Sprague	593D, 595D series	603-224-1961	603-224-1430
Surface-Mount	AVX	X7R	803-946-0690	803-626-3123
Ceramic	Matsuo	X7R	714-969-2491	714-960-6492

# Table 2. Capacitor Selection to MinimizeOutput Resistance

PART	FREQUENCY (kHz)	CAPACITOR (µF)	TYPICAL R <sub>OUT</sub> (Ω)
MAX1697R	12	22	12
MAX1697S	35	6.8	12
MAX1697T	125	2.2	12
MAX1697U	250	1	12

### 

# Table 3. Capacitor Selection to MinimizeCapacitor Size

PART	FREQUENCY (kHz)	CAPACITOR (µF)	TYPICAL R <sub>OUT</sub> (Ω)
MAX1697R	12	10	17
MAX1697S	35	3.3	17
MAX1697T	125	1	17
MAX1697U	250	0.47	17

**MAX1697** 



Figure 4. Cascading MAX1697s to Increase Output Voltage



Figure 5. Paralleling MAX1697s to Reduce Output Resistance



Figure 6. Combined Doubler and Inverter



Figure 7. Heavy Load Connected to a Positive Supply

Chip Information

TRANSISTOR COUNT: 275

## Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
6 SOT23	U6F-6	<u>21-0058</u>



**MAX1697** 

### Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

#### NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM A & LEAD SURFACE.
- 3. PACKAGE DUTLINE EXCLUSIVE DF MDLD FLASH & METAL BURR. MDLD FLASH, PROTRUSION OR METAL BURR SHOULD NOT EXCEED  $0.25\,\text{mm}.$
- 4. PACKAGE DUTLINE INCLUSIVE DF SOLDER PLATING.
- 5. PIN 1 IS LOWER LEFT PIN WHEN READING TOP MARK FROM LEFT TO RIGHT. (SEE EXAMPLE TOP MARK)
- 6. PIN 1 I.D. DOT IS 0.3mm & MIN. LOCATED ABOVE PIN 1.
- 7. MEETS JEDEC MO178, VARIATION AB.
- 8. SOLDER THICKNESS MEASURED AT FLAT SECTION OF LEAD BETWEEN 0.08mm AND 0.15mm FROM LEADTIP.
- 9. LEAD TO BE COPLANAR WITHIN 0.1mm.
- 10. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- 11. MARKING IS FOR PACKAGE DRIENTATION REFERENCE ONLY.

SYMBOL	MIN	NOMINAL	MAX
A	0.90	1.25	1.45
A1	0.00	0.05	0.15
A2	0.90	1.10	1.30
b	0.35	0.40	0.50
С	0.08	0.15	0.20
D	2.80	2.90	3.00
Е	2.60	2.80	3.00
E1	1.50	1.625	1.75
L	0.35	0.45	0.60
L1		0.60 REF	
ei		1.90 BSC	
e		0.95 BSC	
۵	0*	2.5*	10°
	PKG	CODES	
U6-1, U6-2, U6-4, U6C-8, U6SN-1, U6CN-2, U6S-3, U6F-5, U6F-6, U6FH-5, U6FH-6			

		\$ <i>/N/</i> JX		
	PACKAGE (	DUTLINE, SOT 6L BODY		
-DRAWING NOT TO SCALE-	APTROVAL	21-0058	REV.	2/2

## **Revision History**

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
3	12/08	Added additional available top mark for RoHS compliance	1

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